

Electronic Patent Application Fee Transmittal

Application Number:	10723474			
Filing Date:	26-Nov-2003			
Title of Invention:	Electronic apparatus having an adhesive layer from wafer level packaging			
First Named Inventor/Applicant Name:	Suan Jeung Boon			
Filer:	Suneel Arora/Amy Moriarty			
Attorney Docket Number:	303.601US2			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120